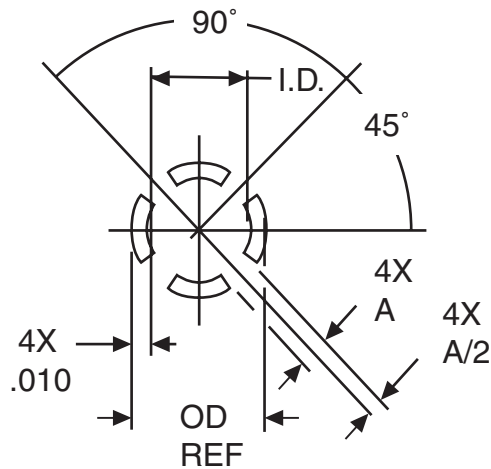


Board 913001 Thermal Pad

1. Drawing of “Thermal Pad” 90° radial .010” wide traces emanating from “Throughhole barrels” and connecting with the copper ground plane.
2. Crescents are void of copper. Traces are “between” the crescents and connect to copper ground plane.

Inner and outer layer conductive planes shall use thermal relief techniques. They are used to ensure adequate barrel heating during soldering for PTH leads that are connected to power and ground layers.

3. Use for U17 - U20, capillary holes 16 - 62 and connector pins



Thermal Relief for Leaded Components

Thermal Pad DIA:

ID = Pad Diameter

OD = ID + .020 inches

A (webs) = .010 inch

Thermal relief is typically only used on barrels used for soldering PTH component leads.



Tel.(714) 898-3830
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Board 913001
Location for Thermal Pads

Component	I.D.	O.D.
U17-U20	0.036	0.056
Hole 16	0.016	0.036
Hole 22	0.022	0.042
Hole 26	0.026	0.046
Hole32	0.032	0.052
Hole 36	0.036	0.056
Hole 40	0.04	0.06
Hole 48	0.048	0.068
Hole 52	0.052	0.072
Hole 57	0.057	0.077
Hole 62	0.062	0.082
Connector	0.0243	0.0443